

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-8. (Canceled)

9. (Previously presented) A method of manufacturing a glass substrate for an information recording medium, comprising the steps of:

immersing the glass substrate in a heated chemical reinforcing treatment liquid, and subjecting an ion on a glass substrate surface layer to ion exchange with an ion in the chemical reinforcing treatment liquid to chemically reinforce the glass substrate; and

treating the surface of the glass substrate drawn up from the chemical reinforcing treatment liquid with a treatment liquid containing silicofluoric acid to control an offset bearing area value to a desired value.

10. (Previously presented) A method of manufacturing a glass substrate for an information recording medium, comprising the steps of:

polishing a glass substrate surface; and

immersing the glass substrate in a heated chemical reinforcing treatment liquid, and subjecting an ion of a glass substrate surface layer to ion exchange with an ion in the chemical reinforcing treatment liquid to chemically reinforce the glass substrate,

said method further comprising the steps of:

controlling the glass substrate surface by a chemical treatment to provide a desired surface roughness before the chemical reinforcing step; and

treating the surface of the glass substrate drawn up from said chemical reinforcing treatment liquid with a treatment liquid containing silicofluoric acid to control an offset bearing area value to a desired value.

11. (Previously presented) The method of manufacturing the glass substrate for the information recording medium according to claim 10 wherein chemical treatment performed before the step of chemically reinforcing the glass substrate comprises treatment with the treatment liquid containing at least one acid selected from the group consisting of sulfuric acid, phosphoric acid, nitric acid, hydrofluoric acid, and silicofluoric acid, or alkali.

12. (Previously presented) The method of manufacturing the glass substrate for the information recording medium according to any one of claims 9 to 11 wherein a concentration of said silicofluoric acid is in a range of 0.01 to 10 wt %.

13. (Previously presented) A method of manufacturing an information recording medium, comprising the steps of forming at least a recording layer on the surface of the information recording medium glass substrate obtained by claims 9 to 12.

14-22. (Canceled)

23. (Previously presented) The manufacturing method according to claim 9, wherein the surface of the substrate is treated with the treatment liquid containing silicofluoric acid so that a bearing area value (offset bearing area value) in a depth of 0.5 to 5 nm (predetermined slice

level) from a bearing height (real peak height) corresponding to the bearing area value of 0.2% to 1.0% is 90% or less.

24. (Previously presented) The manufacturing method according to claim 9, wherein the surface of the substrate is treated with the treatment liquid containing silicofluoric acid so that when a depth corresponds to 20 to 45% of R_{max} from a bearing height (real peak height) corresponding to a bearing area value of 0.2% to 1.0% is set as a slice level, the bearing area value (offset bearing area value) is 90% or less.

25. (Previously presented) The manufacturing method according to claim 10, wherein the surface of the substrate is treated with the treatment liquid containing silicofluoric acid so that a bearing area value (offset bearing area value) in a depth of 0.5 to 5 nm (predetermined slice level) from a bearing height (real peak height) corresponding to the bearing area value of 0.2% to 1.0% is 90% or less.

26. (Previously presented) The manufacturing method according to claim 10, wherein the surface of the substrate is treated with the treatment liquid containing silicofluoric acid so that when a depth corresponds to 20 to 45% of R_{max} from a bearing height (real peak height) corresponding to a bearing area value of 0.2% to 1.0% is set as a slice level, the bearing area value (offset bearing area value) is 90% or less.

27-29. (Canceled)